



Customer: NXP

Part Num: 170-96737

Part Rev:

Job Name: 170-96737-NXP

User Name: Jay Desai

Req. Thick: 62.0

Layer	Base CU / Plt	Thick	Type	Stackup	Subs	Material	Dk	Df
Silkscreen		0.0				Taiyo SS - IJR-4000-FW100		
Soldermask		0.6				Taiyo - PSR-4000 HFX - Green	3.50	0.019
Lyr1	1/2oz / Std	1.9	S					
Prepreg		3.4				EM-827B(i) - 2113-58	4.00	0.019
Lyr2	1oz	1.4	M					
Core		47.0				EM-827(i) - 47.0mils	4.40	0.020
Lyr3	1oz	1.4	M					
Prepreg		3.4				EM-827B(i) - 2113-58	4.00	0.019
Lyr4	1/2oz / Std	1.9	S					
Soldermask		0.6				Taiyo - PSR-4000 HFX - Green	3.50	0.019
Silkscreen		0.0				Taiyo SS - IJR-4000-FW100		

Required Thickness

Type	Req. Thick	Tol% +	Tol% -	Act. Thick	Measured
Overall	62.0	10.0	10.0	61.5	
Over lamination	58.4	10.0	10.0	57.9	
Over laminate	57.1	10.0	10.0	56.6	
Over metal	60.8	10.0	10.0	60.3	

Impedance Constraints

Type	Layer	Design Line	Actual Line	Spacing (traces)	Spacing (ground)	Ref Lyrs	Target (ohms)	Tolerance (ohms)	Predicted (ohms)
Single Ended	Lyr1	12.0	12.9			0 / 2	30.0	3.0	30.1
Single Ended	Lyr1	5.5	5.5			0 / 2	50.0	5.0	49.2
Single Ended	Lyr1	18.0	20.0			0 / 3	100.0	10.0	100.2
Single Ended	Lyr4	12.0	12.9			3 / 0	30.0	3.0	30.1
Single Ended	Lyr4	5.5	5.5			3 / 0	50.0	5.0	49.2
Single Ended	Lyr4	18.0	20.0			2 / 0	100.0	10.0	100.2

Bill of Materials

Material	Type	Qty/Panel	Total
47.0mils - EM-827(i) - 18x24-1/1	core	1	1
1/2oz - 18x24	foil	2	2
2113-58 - EM-827B(i) - 18x24	prepreg	2	2

Comments